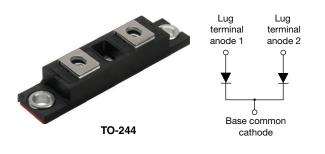
Vishay Semiconductors

HEXFRED[®] Ultrafast Soft Recovery Diode, 240 A



240 A

400 V

197 A at 100 °C

TO-244

Two diodes common cathode

PRIMARY CHARACTERISTICS

I_{F(AV)}

 V_R

I_{F(DC)} at T_C

Package

Circuit configuration

www.vishay.com

FEATURES

- Very low Q_{rr} and t_{rr}
- UL approved file E222165
- · Designed and qualified for industrial level



• Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

BENEFITS

- Reduced RFI and EMI
- Reduced snubbing

DESCRIPTION / APPLICATIONS

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dl_F/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage	VR		400	V	
Continuous forward current	l _F	T _C = 25 °C	395		
		T _C = 100 °C	197	А	
Single pulse forward current	I _{FSM}	Limited by junction temperature	900		
Non-repetitive avalanche energy	E _{AS}	L = 100 μ H, duty cycle limited by maximum T _J	1.4	mJ	
Maximum power dissipation	P _D	T _C = 25 °C	658	W	
		T _C = 100 °C	263	vv	
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C	

ELECTRICAL SPECIFICATIONS ($T_J = 25 \text{ °C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA		400	-	-	
Maximum forward voltage	V _{FM}	I _F = 120 A	See fig. 1	-	1.1	1.47	V
		I _F = 240 A		-	1.3	1.5	
		I _F = 120 A, T _J = 125 °C		-	1.0	1.2	
Maximum reverse leakage current	I _{RM}	T _J = 125 °C, V _R = 400 V	See fig. 2	-	660	5000	μA
Junction capacitance	CT	V _R = 200 V	See fig. 3	-	280	380	pF
Series inductance	L _S	From top of terminal hole to mounting plane		-	6.0	-	nH

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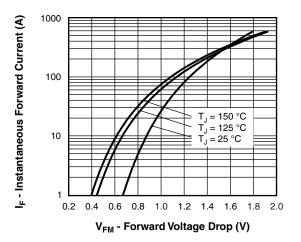
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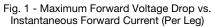
DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25$ °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5	t _{rr}	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200 \text{ A}/\mu\text{s}, \text{ V}_R = 30 \text{ V}$		-	50	-	
		T _J = 25 °C	I _F = 140 A dI _F /dt = 200 A/μs V _R = 200 V	-	77	120	ns
		T _J = 125 °C		-	290	440	
Peak recovery current See fig. 6	I _{RRM}	T _J = 25 °C		-	7.5	14	А
		T _J = 125 °C		-	16	30	
Reverse recovery charge See fig. 7	Q _{rr}	T _J = 25 °C		-	290	780	nC
		T _J = 125 °C		-	2300	6300	
Peak rate of recovery current See fig. 8	dl _{(rec)M} /dt	T _J = 25 °C		-	320	-	A/µs
		T _J = 125 °C		-	270	-	

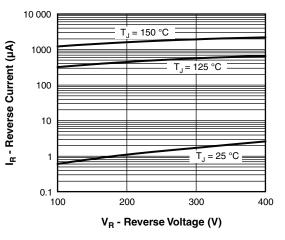
THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range		T _J , T _{Stg}	- 55	-	150	°C	
Thermal resistance, junction to case	per leg	– R _{thJC}	-	-	0.19	°C/W	
	per module		-	-	0.095		
Typical thermal resistance, case to heatsink		R _{thCS}	-	0.10	-		
Weight			-	68	-	g	
Weight			-	2.4	-	oz.	
Mounting torgue ⁽¹⁾			30 (3.4)	-	40 (4.6)	lbf ⋅ in (N ⋅ m)	
Mounting torque (%	center hole		12 (1.4)	-	18 (2.1)		
Terminal torque			30 (3.4)	-	40 (4.6)	()	
Vertical pull 2" lever pull			-	-	80	lbf ⋅ in	
			-	-	35	חויוטו	

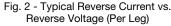
Note

(1) Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf · in steps until desired or maximum torque limits are reached









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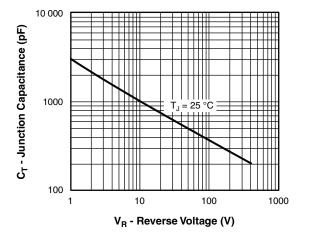


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

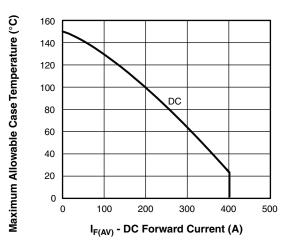


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

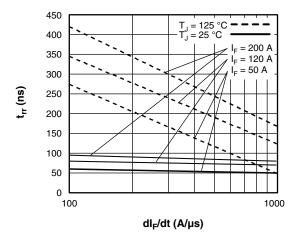


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

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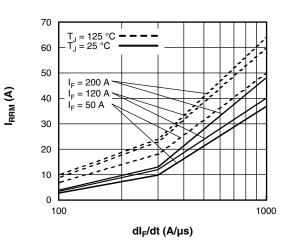
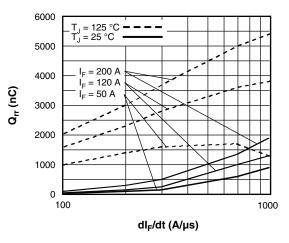
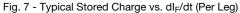


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)





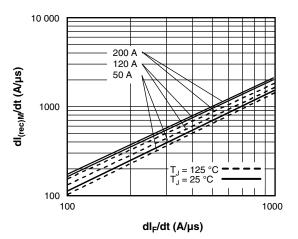


Fig. 8 - Typical dI(rec)M/dt vs. dIF/dt (Per Leg)

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VS-HFA240NJ40CPbF www.vishay.com **Vishay Semiconductors** 1 Z_{thJC} - Thermal Response 0.1 D = 0.50D = 0.33 0.01 [►]D = 0.25 $\sum_{n=0.17}^{\infty} D = 0.17$ ⁻D = 0.08 Single pulse (thermal response) 1 1 1 1 1 1 1 0.001 0.00001 0.001 0.0001 0.01 0.1 1 10 t₁ - Rectangular Pulse Duration (s)

Fig. 9 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

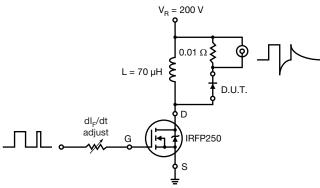
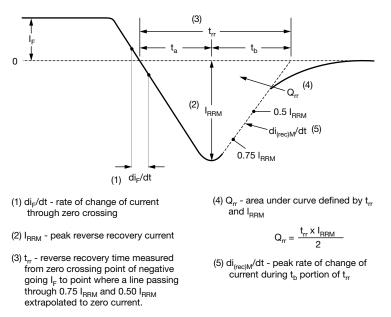
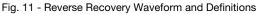


Fig. 10 - - Reverse Recovery Parameter Test Circuit





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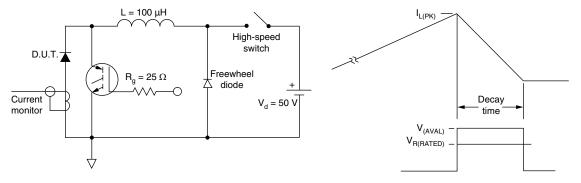
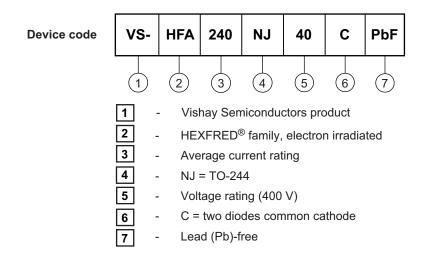


Fig. 12 - Avalanche Test Circuit and Waveforms

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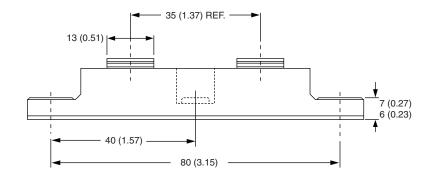


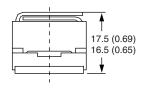


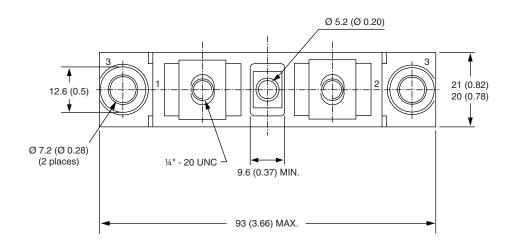
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TO-244

DIMENSIONS in millimeters (inches)









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